

# N-Channel MOSFET

## 100V 70A 62.5W DFN5X6

MFT10N70D56

MERITEK

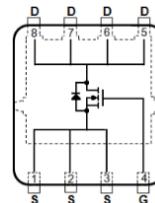
### FEATURE

- $R_{DS(ON)} < 7.2\text{m}\Omega$ ,  $V_{GS} = 10\text{V}$ ,  $I_D = 20\text{A}$
- $R_{DS(ON)} < 10.5\text{m}\Omega$ ,  $V_{GS} = 4.5\text{V}$ ,  $I_D = 10\text{A}$
- High Power and Current Handling Capability
- Super High Dense Cell Design For Extremely Low  $R_{DS(ON)}$



### MECHANICAL DATA

- Case: Molded Plastic, DFN5060 Package
- Terminal: Solderable per MIL-STD-750, Method 2026



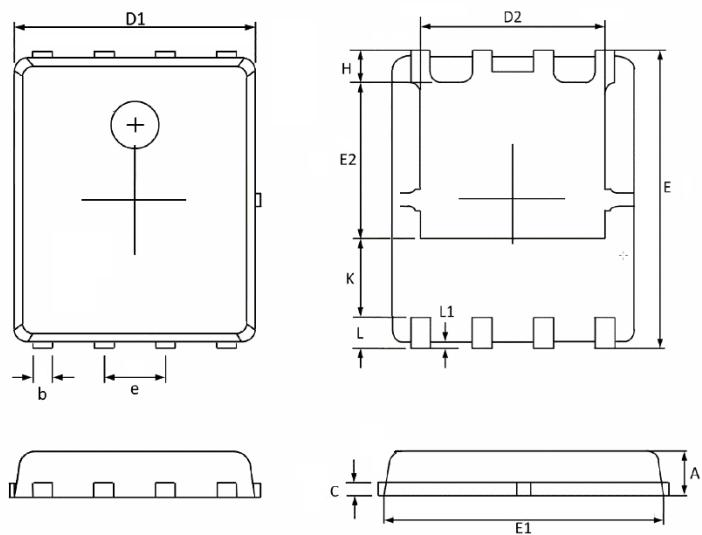
RoHS

### MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current – Continuous	$I_D$ at $R_{\theta JA}$	22	A
	$I_D$ at $R_{\theta JC}$	70	A
Drain Current – Pulsed	$I_{DM}$ at $R_{\theta JA}$	88	A
	$I_{DM}$ at $R_{\theta JC}$	280	A
Avalanche Current	$I_{AS}$	20	A
Avalanche Energy	$E_{AS}$	200	mJ
Power Dissipation	$P_D$	62.5	W
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	20	$^{\circ}\text{C}/\text{W}$
Thermal Resistance, Junction to Case	$R_{\theta JC}$	2	$^{\circ}\text{C}/\text{W}$
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	$^{\circ}\text{C}$

### DIMENSIONS

Item	Min (mm)	Max (mm)
A	0.80	1.10
b	0.33	0.51
C	0.20	0.30
D1	4.80	5.10
D2	3.61	4.10
E	5.90	6.20
E1	5.70	5.90
E2	3.35	3.78
e	1.27BSC	
H	0.41	0.70
K	1.10	1.50
L	0.51	0.71
L1	0.06	0.20



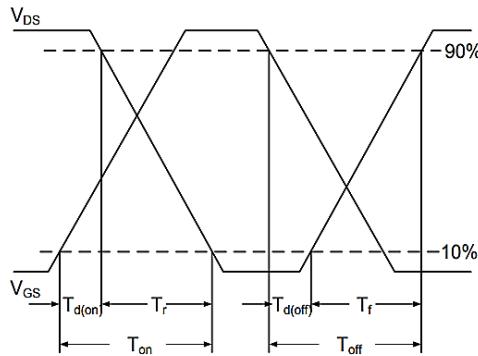
## ELECTRICAL CHARACTERISTICS

Off Characteristics	Conditions	Symbol	Min	Typ.	Max	Unit
<b>Drain-Source Breakdown Voltage</b>	$V_{GS}=0V, I_D=250\mu A$	$BV_{DSS}$	100	--	--	V
<b>Drain-Source Leakage Current</b>	$V_{DS}=100V, V_{GS}=0V$	$I_{DSS}$	--	--	1	$\mu A$
<b>Gate Leakage Current, Forward</b>	$V_{GS}=20V, V_{DS}=0V$	$I_{GSSF}$	--	--	100	nA
<b>Gate Leakage Current, Reverse</b>	$V_{GS}=-20V, V_{DS}=0V$	$I_{GSSR}$	--	--	-100	nA
On Characteristics	Conditions	Symbol	Min	Typ.	Max	Unit
<b>Static Drain-Source On-Resistance</b>	$V_{GS}=10V, I_D=20A$	$R_{DS(ON)}$	--	6.0	7.2	$m\Omega$
	$V_{GS}=4.5V, I_D=10A$		--	8.3	10.5	$m\Omega$
<b>Gate Threshold Voltage</b>	$V_{GS}=V_{DS}, I_D=250\mu A$	$V_{GS(th)}$	1	--	3	V
Dynamic Characteristics	Conditions	Symbol	Min	Typ.	Max	Unit
<b>Total Gate Charge</b>	$V_{DS}=80V, V_{GS}=4.5V, I_D=20A$	$Q_g$	-	22	-	nC
<b>Gate-Source Charge</b>		$Q_{gs}$	-	5	-	nC
<b>Gate-Drain Charge</b>		$Q_{gd}$	-	14	-	nC
<b>Turn-On Delay Time</b>		$T_{d(on)}$	-	17	-	ns
<b>Rise Time</b>	$V_{DS}=80V, V_{GS}=10V, R_G=6\Omega, I_D=20A$	$T_r$	-	9	-	ns
<b>Turn-Off Delay Time</b>		$T_{d(off)}$	-	54	-	ns
<b>Fall Time</b>		$T_f$	-	15	-	ns
<b>Input Capacitance</b>		$C_{iss}$	-	1895	-	pF
<b>Output Capacitance</b>	$V_{DS}=50V, V_{GS}=0V, F=1MHz$	$C_{oss}$	-	405	-	pF
<b>Reverse Transfer Capacitance</b>		$C_{rss}$	-	20	-	pF
Drain-Source Body Diode	Conditions	Symbol	Min	Typ.	Max	Unit
<b>Diode Forward Current-Continuous</b>	--	$I_s$	--	--	40	A
<b>Diode Forward Voltage</b>	$V_{GS}=0V, I_s=10A$	$V_{SD}$	--	--	1.5	V

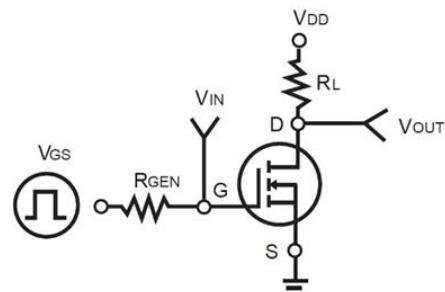
Note:

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$
4. Guaranteed by design, not subject to production testing
5.  $L = 1mH, I_{AS} = 20A, V_{DD} = 50V, R_G = 25\Omega$ , Starting  $T_J = 25^\circ C$

Switching Time Waveform



Switching Test Circuit

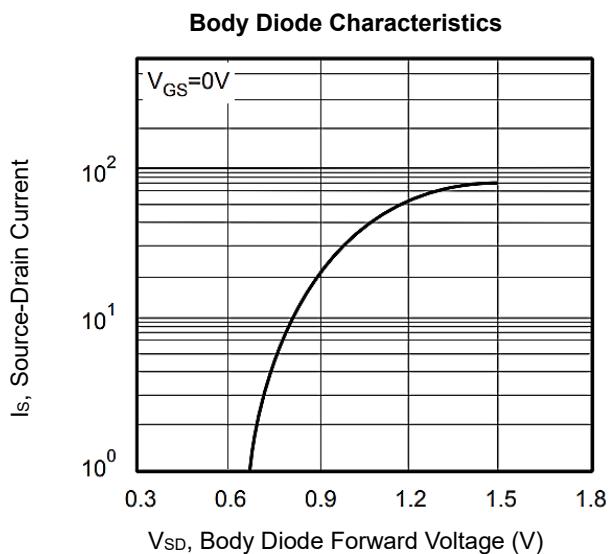
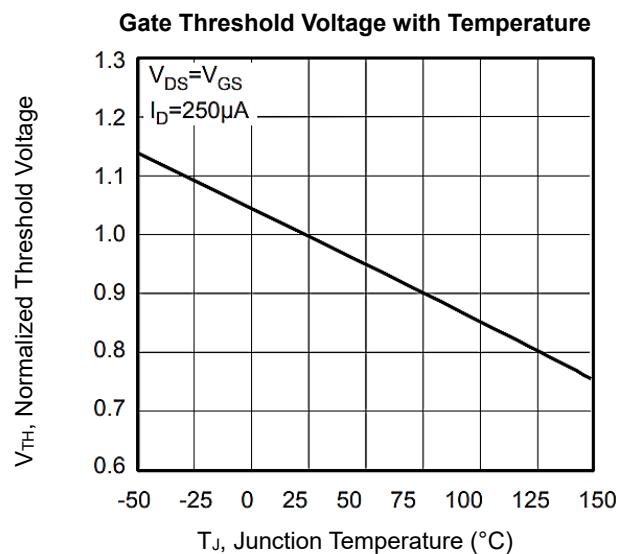
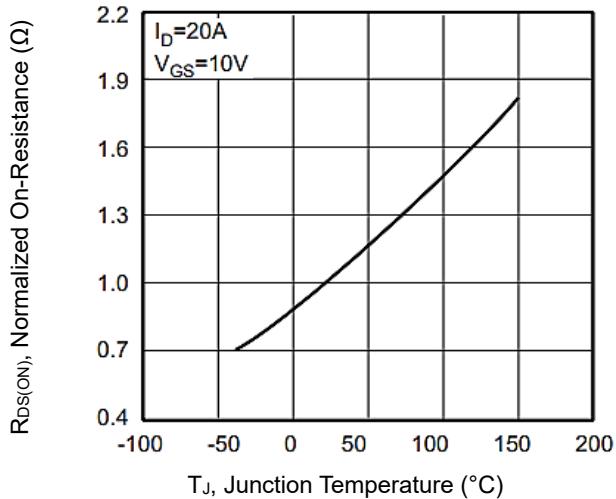
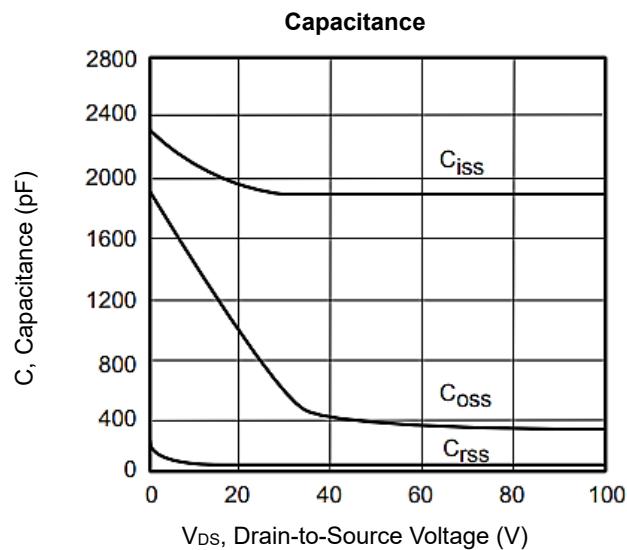
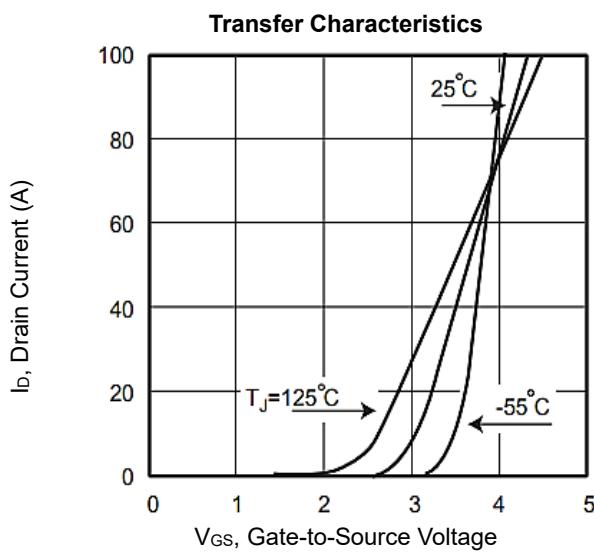
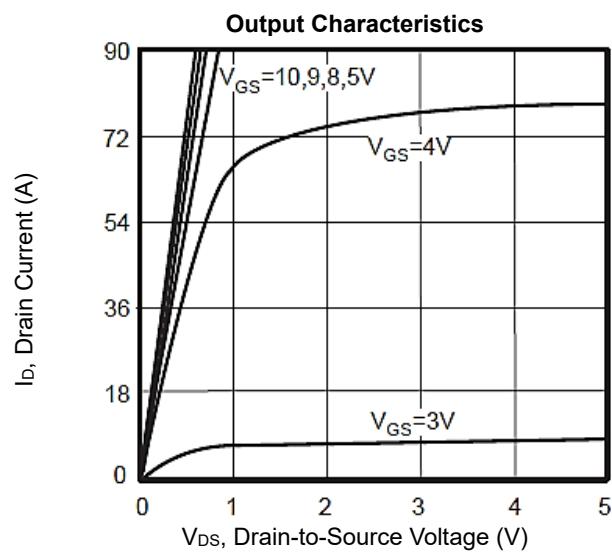


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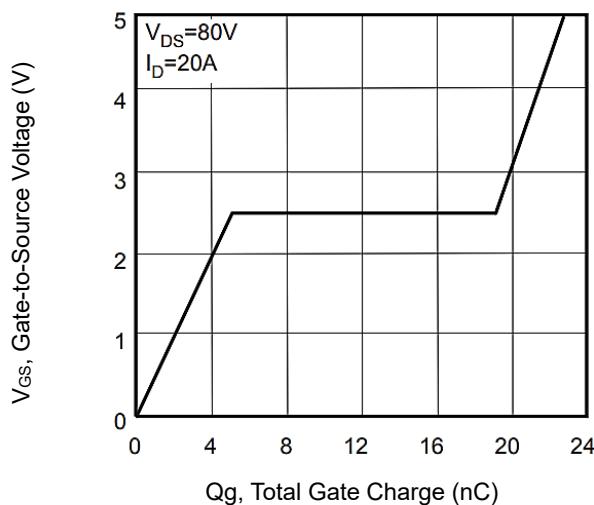
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**CHARACTERISTICS CURVES**

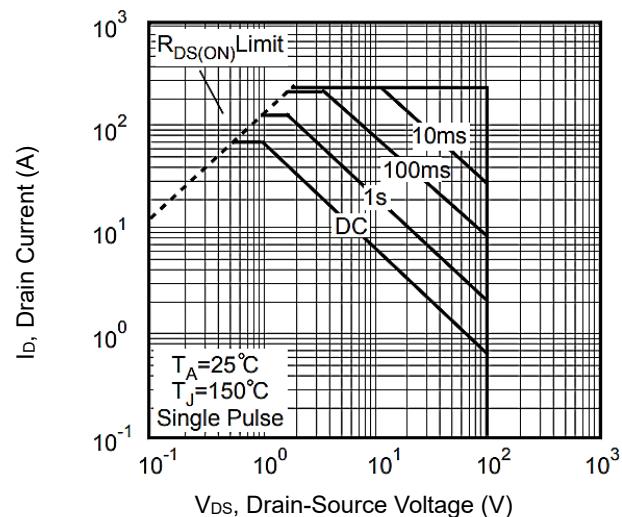


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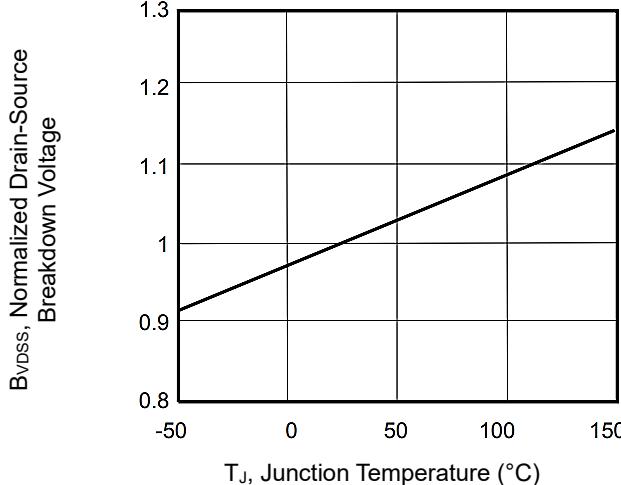
Gate Charge



Maximum Safe Operating Area



Breakdown Voltage Variation with Temperature



Transient Thermal Response Curves

